

Amendments of the Claims:

A detailed listing of all claims in the application is presented below. This listing of claims will replace all prior versions, and listings, of claims in the application. All claims being currently amended are submitted with markings to indicate the changes that have been made relative to immediate prior version of the claims. The changes in any amended claim are being shown by strikethrough (for deleted matter) or underlined (for added matter).

1. (Currently amended) A structure of memory card comprising:

a base plate on which IC chips are connected;

a case mounted to the base plate and at least one window defined through the case so that at least one of the IC chips is accommodated in the at least one window, a space enclosed by the at least one window being larger than the at least one of the IC chips and a top surface of the at least one of the IC chips accommodated in the at least one window being in flush with a top surface of the case, and

a top seal plate attached on the case and sealing the at least one window;

whereby a conventional, thicker IC chip can be accommodated in the window region with the top seal plate attached thereon sealing the window.

2. (Original) The device as claimed in claim 1, wherein the IC chips have connection legs electrically connected to the base plate.

3 (Canceled)

4. (Currently amended) A structure of memory card comprising:

a base plate on which IC chips are connected;

a case mounted to the base plate and at least one window defined through the case

so that at least one of the IC chips is accommodated in the at least one window, a space enclosed by the at least one window being slightly larger than the at least one of the IC chips and a top surface of the at least one of the IC chips accommodated in the at least one window being in flush with a top surface of the case, a periphery of the at least one of the IC chips being fitted and in contact with an inner periphery of the at least one window, and

a top seal plate attached on the case and sealing the at least one window;

whereby a conventional, thicker IC chip can be accommodated in the window region with the top seal plate attached thereon sealing the window.

5. (New) The structure of claim 1, wherein the IC chips comprises flash chip.
6. (New) The structure of claim 4, wherein the IC chips comprises flash chip.
7. (New) The structure of claim 1, wherein the IC chips comprises passive chip.
8. (New) The structure of claim 4, wherein the IC chips comprises passive chip.
9. (New) The structure of claim 1, wherein the IC chips comprises controller chip.
10. (New) The structure of claim 4, wherein the IC chips comprises controller chip.
11. (New) The structure of claim 1, wherein the structure comprises a memory card.

12. (New) The structure of claim 4, wherein the structure comprises a memory card.